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IN THE CLAIMS

1. (Currently Amended) An IC card comprising:

an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate; and

a core layer comprising a plurality of sheet materials having said IC module disposed therebetween,

wherein, in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole for containing therein said IC chip, formed in a region corresponding to an IC mounted portion of said IC module,

wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module,

wherein a relationship $A = (B1 + C1) \pm 30 \mu m$ is satisfied,

where A (μ m) represents the sum of heights of said through holes, B1 (μ m) represents a projection height on an IC mounted surface of said IC module, and C1 (μ m) represents a projection height on an IC non-mounted surface of said IC module.

- 2. (Original) The IC card according to claim 1, wherein a relationship (B1 + C1) $20 \mu m \le A \le (B1 + C1) + 10 \mu m$ is satisfied.
- 3. (Original) The IC card according to claim 1, wherein a relationship $B = B1 \pm 30 \,\mu m$ is satisfied where B (μm) represents a height of said through hole on the side of the IC mounted surface of said IC module.
- 4. (Original) The IC card according to claim 1, wherein a relationship $C = C1 \pm 30 \mu m$ is satisfied where C (μm) represents a height of said through hole on the side of the IC non-mounted surface of said IC module.

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5. (Original) The IC card according to claim 1, wherein a relationships $B = B1 \pm 30 \mu m$, and $C = C1 \pm 30 \mu m$ are satisfied where B (μm) represents a height of said through hole on the side of the IC mounted surface of said IC module, and C (μm) represents a height of said through hole on the side of the IC non-mounted surface of said IC module.

- 6. (Currently Amended) The IC card according to claim 1, wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module, and an outer core sheet stacked on at least one of said pair of inner core sheets.
- 7. (Original) The IC card according to claim 1, wherein said core layer has a rewritable display layer formed on at least one surface of said core layer.
- 8. (Original) The IC card according to claim 1, wherein, in said sheet materials constituting said core layer, at least a pair of sheet materials having said IC module disposed therebetween includes a material comprising a copolymer of terephthalic acid, cyclohexanedimethanol and ethylene glycol, and polycarbonate.
- 9. (Original) The IC card according to claim 1, wherein said sheet materials constituting said core layer comprise a no-chlorine-containing material.
 - 10. (Currently Amended) An IC card comprising:

an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate; and

a core layer comprising a plurality of sheet materials having said IC module disposed therebetween,

wherein, in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole for containing therein said IC chip, formed in a region corresponding to an IC mounted portion of said IC module,

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wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module,

wherein a relationships $B = B1 \pm 30~\mu m$, and $C = C1 \pm 30~\mu m$ are satisfied, where $B1~(\mu m)$ represents a projection height on an IC mounted surface of said IC module, $C1~(\mu m)$ represents a projection height on an IC non-mounted surface of said IC module, $B~(\mu m)$ represents a height of said through hole on the side of the IC mounted surface of said IC module, and $C~(\mu m)$ represents a height of said through hole on the side of the IC non-mounted surface of said IC module.

- 11. (Original) The IC card according to claim 10, wherein a relationship $A = (B1 + C1) \pm 30 \mu m$ is satisfied where A (μm) represents the sum of heights of said through holes.
- 12. (Original) The IC card according to claim 10, wherein a relationship (B1 + C1) 20 μ m \leq A \leq (B1 + C1) + 10 μ m is satisfied.
- 13. (Currently Amended) The IC card according to claim 10, wherein said plurality of sheet materials constituting said core layer comprise at least a pair of inner core sheets adjacent to said IC module, and an outer core sheet stacked on at least one of said pair of inner core sheets.
- 14. (Original) The IC card according to claim 10, wherein said core layer has a rewritable display layer formed on at least one surface of said core layer.
- 15. (Original) The IC card according to claim 10, wherein, in said sheet materials constituting said core layer, at least a pair of sheet materials having said IC module disposed therebetween comprise a material comprising a copolymer of terephthalic acid, cyclohexanedimethanol, and ethylene glycol and polycarbonate.
- 16. (Original) The IC card according to claim 10, wherein said sheet materials constituting said core layer comprise a no-chlorine-containing material.

17. (Previously Presented) An IC card comprising:

an IC module which comprises an IC chip mounted on an insulating substrate having an antenna coil, and a chip reinforcing plate provided on at least an IC mounted surface of said insulating substrate; and

a core layer comprising a plurality of sheet materials having said IC module disposed therebetween,

wherein, in said plurality of sheet materials, at least the sheet materials adjacent to said IC module have a through hole for containing therein said IC chip, formed in a region corresponding to an IC mounted portion of said IC module,

wherein A = (B1 + C1), where A (μm) represents the sum of heights of said through holes, B1 (μm) represents a projection height on an IC mounted surface of said IC module, and C1 (μm) represents a projection height on an IC non-mounted surface of said IC module, wherein A is no greater or no less than 30 microns from the sum of B_1 and C_1 .

- 18. (Previously Presented) The IC card according to claim 17, wherein a relationship (B1 + C1) 20 μ m \leq A \leq (B1 + C1) + 10 μ m is satisfied.
- 19. (Previously Presented) The IC card according to claim 17, wherein a relationship $B = B1 \pm 30 \,\mu m$ is satisfied where B (μm) represents a height of said through hole on the side of the IC mounted surface of said IC module.
- 20. (Previously Presented) The IC card according to claim 17, wherein a relationship $C = C1 \pm 30 \,\mu m$ is satisfied where C (μm) represents a height of said through hole on the side of the IC non-mounted surface of said IC module.